inter_{sil}"

Single and Dual Single Supply Ultra-Low Noise, Low Distortion Rail-to-Rail Output, Op Amp

ISL28191, ISL28291

The ISL28191 and ISL28291 are tiny single and dual ultra-low noise, ultra-low distortion operational amplifiers. They are fully specified to operate down to +3V single supply. These amplifiers have outputs that swing rail-to-rail and an input common mode voltage that extends to ground (ground sensing).

The ISL28191 and ISL28291 are unity gain stable with an input referred voltage noise of 1.7nV/ \sqrt{Hz} . Both parts feature 0.00018% THD+N at 1kHz.

The ISL28191 is available in the space-saving 6 Ld UTDFN (1.6mmx1.6mm) and 6 Ld SOT-23 packages. The ISL28291 is available in the 8 Ld SOIC, 10 Ld 1.8mmx1.4mm UTQFN and 10 Ld MSOP packages. All devices are guaranteed over -40 °C to +125 °C.

Ordering Information

PART NUMBER (Note 5)	PART MARKING	PACKAGE (Pb-free)	PKG. DWG. #		
ISL28191FHZ-T7 (Notes 1, 2)	GABJ	6 Ld SOT-23 (Note 4)	P6.064A		
ISL28191FRUZ-T7 (Notes 1, 3)	M8	6 Ld UTDFN	L6.1.6x1.6A		
ISL28291FUZ (Note 2)	8291Z	10 Ld MSOP	M10.118A		
ISL28291FUZ-T7 (Notes 1, 2)	8291Z	10 Ld MSOP	M10.118A		
ISL28291FBZ (Note 2)	28291 FBZ	8 Ld SOIC	M8.15E		
ISL28291FBZ-T7 (Notes 1, 2)	28291 FBZ	8 Ld SOIC	M8.15E		
ISL28291FRUZ-T7 (Notes 1, 3)	F	10 Ld UTQFN	L10.1.8x1.4A		
ISL28191EVAL1Z	Evaluation Board				
ISL28291EVAL1Z	Evaluation Board				

NOTES:

- 1. Please refer to TB347 for details on reel specifications.
- 2. These Intersil Pb-free plastic packaged products employ special Pbfree material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pbfree requirements of IPC/JEDEC J STD-020.
- 3. These Intersil Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and NiPdAu plate e4 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.
- 4. The part marking is located on the bottom of the part.
- 5. For Moisture Sensitivity Level (MSL), please see device information page for <u>ISL28191, ISL28291</u>. For more information on MSL please see techbrief TB363.

Features

- 1.7nV/ \sqrt{Hz} input voltage noise at 1kHz
- + 1kHz THD+N typical 0.00018% at $2V_{P-P} V_{OUT}$
- Harmonic Distortion -76dBc, -70dBc, f_o = 1MHz
- 61MHz -3dB bandwidth
- 630µV maximum offset voltage
- 3µA input bias current
- 100dB typical CMRR
- 3V to 5.5V single supply voltage range
- Rail-to-rail output
- Ground Sensing
- Enable pin (not available in the 8 Ld SOIC package option)
- Pb-free (RoHS compliant)

Applications

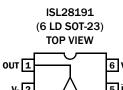
- · Low noise signal processing
- · Low noise microphones/preamplifiers
- ADC buffers
- DAC output amplifiers
- Digital scales
- Strain gauges/sensor amplifiers
- Radio systems
- Portable equipment
- Infrared detectors

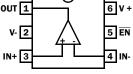
Related Literature

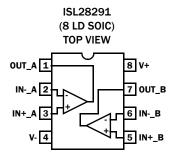
• <u>AN1343</u>: ISL2829xEVAL1Z, ISL5529xEVAL1Z Evaluation Board User's Guide

1

Pin Configurations





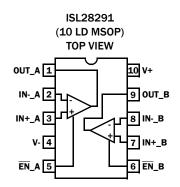


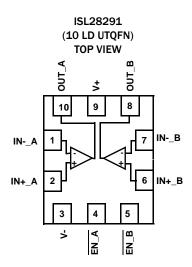
|3 .⊢₽

IN+

4 V-

4





Pin Descriptions

ISL28191 (6 Ld SOT-23)	ISL28191 (6 Ld UTDFN)	ISL28291 (8 Ld SOIC)	ISL28291 (10 Ld MSOP)	ISL28291 (10 Ld UTQFN)	PIN NAME	FUNCTION	EQUIVALENT CIRCUIT
4	2	2 (A) 6 (B)	2 (A) 8 (B)	1 (A) 7 (B)	IN- INA INB	Inverting input	
3	3	3 (A) 5 (B)	3 (A) 7 (B)	2 (A) 6 (B)	IN+ IN+_B IN+_B	Non-inverting input	(See circuit 1)
2	4	4	4	3	V-	Negative supply	
1	1	1 (A) 7 (B)	1 (A) 9 (B)	10 (A) 8 (B)	OUT_A OUT_B	Output	
6	6	8	10	9	V+	Positive supply	
5	5	N/A	5 (A) 6 (B)	4 (A) 5 (B)	EN_A EN_A EN_B	Enable BAR pin internal pull-down; Logic "1" selects the disabled state; Logic "0" selects the enabled state.	EN D V+

Absolute Maximum Ratings (T_A = +25°C)

Supply Voltage
Supply Turn On Voltage Slew Rate 1V/µs
Differential Input Current 5mA
Differential Input Voltage0.5V
Input Voltage
ESD Tolerance
Human Body Model
Machine Model
Charged Device Model (CDM)

Thermal Information

Thermal Resistance (Typical, Note 6)	θ JA (°C/W)
6 Ld SOT-23 Package	230
6 Ld UTDFN Package	125
8 Ld SOIC Package	110
10 Ld MSOP Package	150
10 Ld UTQFN Package	143
Storage Temperature Range65	°C to +150 °C
Pb-Free Reflow Profile	see link below
http://www.intersil.com/pbfree/Pb-FreeReflow.asp	

Operating Conditions

Ambient Operating Temperature Range	40°C to +125°C
Maximum Operating Junction Temperature	+125°C
Supply Voltage	3V to 5.5V

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

NOTE:

6. θ_{JA} is measured with the component mounted on a high effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

PARAMETER	DESCRIPTION	DESCRIPTION CONDITIONS		ТҮР	MAX (Note 7)	UNIT
DC SPECIFICAT	ONS		I		1	
V _{OS}	Input Offset Voltage			270	630 840	μV
$\frac{\Delta V_{\text{OS}}}{\Delta T}$	Input Offset Drift vs Temperature	Figure 21		3.1		µV∕°C
IIO	Input Offset Current			35	500 900	nA
IB	Input Bias Current			3	6 7	μA
CMIR	Common-Mode Input Range		0		3.8	v
CMRR	Common-Mode Rejection Ratio	V _{CM} = 0V to 3.8V	78	100		dB
PSRR	Power Supply Rejection Ratio	$V_{S} = 3V \text{ to } 5V$	74	80		dB
A _{VOL}	Large Signal Voltage Gain	$V_0 = 0.5V$ to 4V, $R_L = 1k\Omega$	90 86	98		dB
V _{OUT}	Maximum Output Voltage Swing	Output low, $R_L = 1k\Omega$		20	50 80	mV
		Output high, $R_L = 1k\Omega$, V+ = 5V	4.95 4.92	4.97		v
I _{S,ON}	Supply Current per Amplifier, Enabled			2.6	3.5 3.9	mA
I _{S,OFF}	Supply Current per Amplifier, Disabled			26	35 48	μA
I ₀ +	Short-Circuit Output Current	$R_L = 10\Omega$	95 90	130		mA
I ₀ -	Short-Circuit Output Current	R _L = 10Ω	95 90	130		mA
V _{SUPPLY}	Supply Operating Range	V+ to V-	3		5.5	v

Electrical Specifications V+ = 5.0V, V- = GND, R_L = Open, R_F = $1k\Omega$, A_V = -1 unless otherwise specified. Parameters are per amplifier. Typical values are at V+= 5V, T_A = +25°C. Boldface limits apply over the operating temperature range, -40°C to +125°C.

ISL28191, ISL28291

Electrical Specifications V+ = 5.0V, V- = GND, R_L = Open, R_F = 1k Ω , A_V = -1 unless otherwise specified. Parameters are per amplifier. Typical values are at V+= 5V, T_A = +25°C. Boldface limits apply over the operating temperature range, -40°C to +125°C. (Continued)

PARAMETER	DESCRIPTION	CONDITIONS	MIN (Note 7)	ТҮР	MAX (Note 7)	UNIT
VENH	EN High Level	Referred to V-	2			v
VENL	EN Low Level	Referred to V-			0.8	v
IENH	EN Pin Input High Current	$V_{\overline{EN}} = V +$		0.8	1.1 1.3	μA
IENL	EN Pin Input Low Current	$V_{\overline{EN}} = V_{-}$		20	80 100	nA
AC SPECIFICATIO	ONS		1	1		1
GBW	-3dB Unity Gain Bandwidth	$\textbf{R}_{\textbf{F}} = \textbf{0}\boldsymbol{\Omega}, \textbf{C}_{\textbf{L}} = \textbf{2}\textbf{0}\textbf{p}\textbf{F}, \textbf{A}_{\textbf{V}} = \textbf{1}, \textbf{R}_{\textbf{L}} = \textbf{1}\textbf{0}\textbf{k}\boldsymbol{\Omega}$		61		MHz
THD+N	Total Harmonic Distortion + Noise	f = 1kHz. V _{OUT} + 2V _{P-P} , A _V = +1, R _L = 10k Ω		0.0001 8		%
HD	2nd Harmonic Distortion	$2V_{P-P}$ output voltage, $A_V = 1$		-76		dBc
(1MHz)	3rd Harmonic Distortion	-		-70		dBc
ISO	Off-state Isolation f _O = 100kHz			-38		dB
X-TALK ISL28291	Channel-to-Channel Crosstalk f ₀ = 100kHz	alk $V_{S} = \pm 2.5V, A_{V} = \pm 1, V_{IN} = 1V_{P-P},$ $R_{F} = 0\Omega, C_{L} = 20pF, A_{V} = 1, R_{L} = 10k\Omega$		-105		dB
PSRR	Power Supply Rejection Ratio f ₀ = 100kHz	$\label{eq:VS} \begin{split} &V_S = \pm 2.5 \text{V}, \text{A}_V = \pm 1, \text{V}_{SOURCE} = 1 \text{V}_{\text{P-P}} \\ &R_F = 0 \Omega, \text{C}_L = 20 \text{pF}, \text{A}_V = 1, \text{R}_L = 10 \text{k} \Omega \end{split}$		-70		dB
CMRR	Common Mode Rejection Ratio f _O = 100kHz			-65		dB
e _n	Input Referred Voltage Noise	f _O = 1kHz		1.7		nV/√Hz
i _n	Input Referred Current Noise	f _O = 1kHz		1.8		pA/√Hz
TRANSIENT RES	PONSE					
SR	Slew Rate		12 12	17		V/µs
t _r , t _f , Small	Rise Time, t _r 10% to 90%	$\textbf{A}_{\textbf{V}} = \textbf{1}, \textbf{V}_{\textbf{OUT}} = \textbf{0}.\textbf{1}\textbf{V}_{\textbf{P-P}}, \textbf{R}_{\textbf{L}} = \textbf{1}\textbf{0}\textbf{k}\boldsymbol{\Omega}, \textbf{C}_{\textbf{L}} = \textbf{1}.\textbf{2}\textbf{p}\textbf{F}$		7		ns
Signal	Fall Time, t _f 90% to 10%	-		12		ns
t _r , t _f Large Signal	Rise Time, t _r 10% to 90%	$A_V = 2$, $V_{OUT} = 1V_{P-P}$; $R_L = 10k\Omega$,		44		ns
	Fall Time, t _f 90% to 10%	$R_{F}/R_{G} = 499\Omega/499\Omega, C_{L} = 1.2pF$		50		ns
	Rise Time, t _r 10% to 90%	$A_V = 2, V_{OUT} = 4.7V_{P-P}; R_L = 10k\Omega,$		190		ns
	Fall Time, t _f 90% to 10%	$R_{F}/R_{G} = 499\Omega/499\Omega, C_{L} = 1.2pF$		190		ns
t _{EN}	ENABLE to Output Turn-on Delay Time; 10% EN - 10% V _{OUT}	$A_V = 1, V_{OUT} = 1VDC, R_L = 10k\Omega, C_L = 1.2pF$		330		ns
	ENABLE to Output Turn-off Delay Time; 10% EN - 10% V _{OUT}	$A_V = 1, V_{OUT} = OVDC, R_L = 10k\Omega, C_L = 1.2pF$		50		ns

NOTE:

7. Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design.

Typical Performance Curves

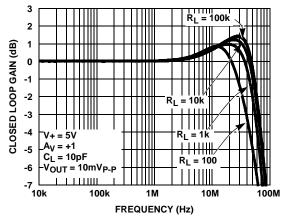


FIGURE 1. GAIN vs FREQUENCY FOR VARIOUS RLOAD

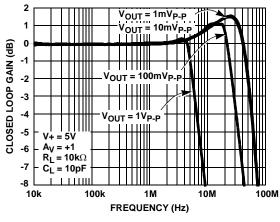


FIGURE 3. -3dB BANDWIDTH vs VOUT

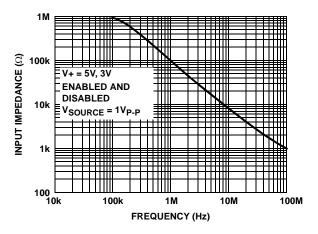


FIGURE 5. INPUT IMPEDANCE vs FREQUENCY

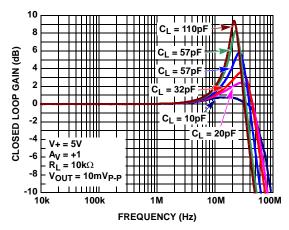


FIGURE 2. GAIN vs FREQUENCY FOR VARIOUS CLOAD

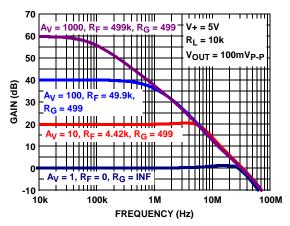


FIGURE 4. FREQUENCY RESPONSE vs CLOSED LOOP GAIN

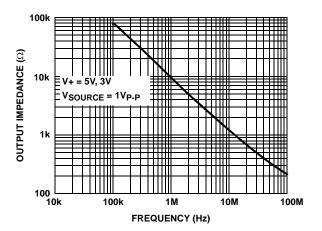


FIGURE 6. DISABLED OUTPUT IMPEDANCE vs FREQUENCY

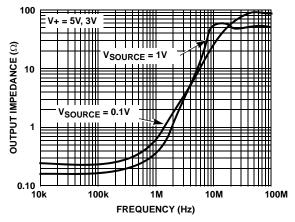


FIGURE 7. ENABLED OUTPUT IMPEDANCE vs FREQUENCY

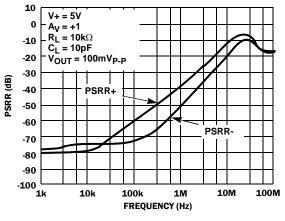


FIGURE 9. PSRR vs FREQUENCY

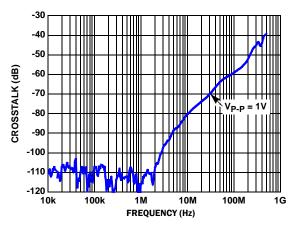


FIGURE 11. CHANNEL TO CHANNEL CROSSTALK vs FREQUENCY

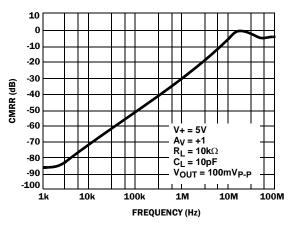


FIGURE 8. CMRR vs FREQUENCY

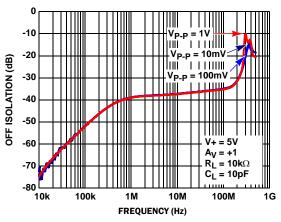


FIGURE 10. OFF ISOLATION vs FREQUENCY

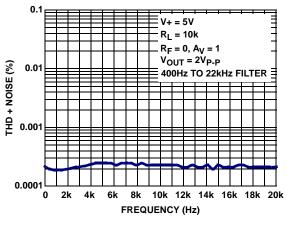


FIGURE 12. THD+N vs FREQUENCY

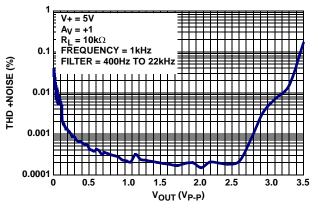


FIGURE 13. THD+N @ 1kHz vs VOUT

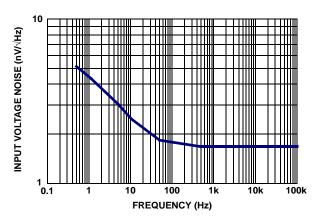


FIGURE 14. INPUT REFERRED NOISE VOLTAGE vs FREQUENCY

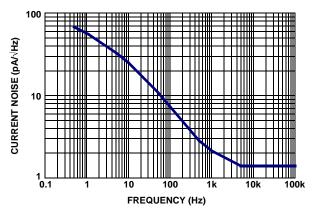


FIGURE 15. INPUT REFERRED NOISE CURRENT vs FREQUENCY

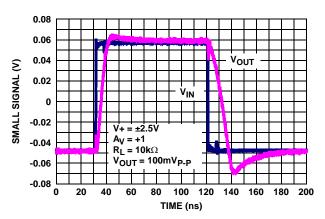
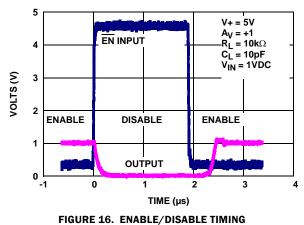


FIGURE 17. SMALL SIGNAL STEP RESPONSE



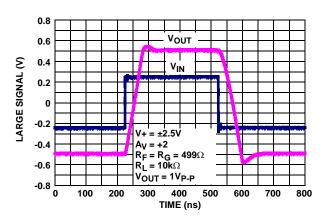


FIGURE 18. LARGE SIGNAL (1V) STEP RESPONSE

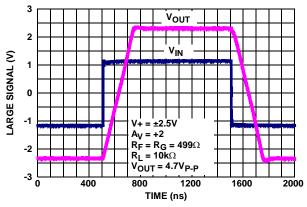
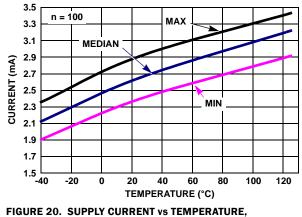


FIGURE 19. LARGE SIGNAL (4.7V) STEP RESPONSE



GURE 20. SUPPLY CURRENT vs TEMPERATURE $V_S = \pm 2.5V$ ENABLED, $R_L = INF$

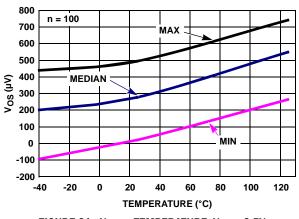


FIGURE 21. V_{OS} vs TEMPERATURE, $V_S = \pm 2.5V$

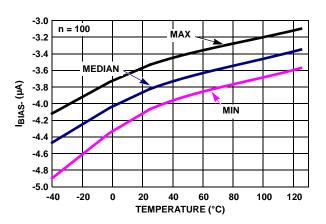


FIGURE 23. IBIAS- vs TEMPERATURE, VS = ±2.5V

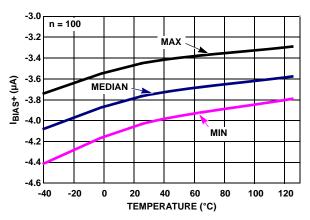


FIGURE 22. I_{BIAS+} vs TEMPERATURE, $V_S = \pm 2.5V$

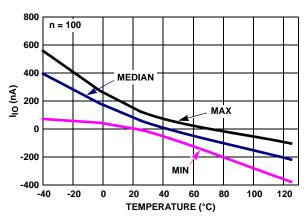
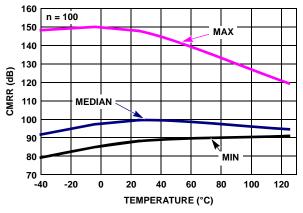


FIGURE 24. I_{IO} vs TEMPERATURE, V_S = ±2.5V





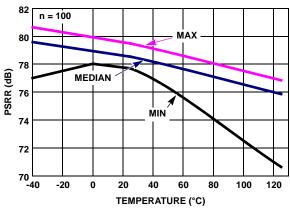
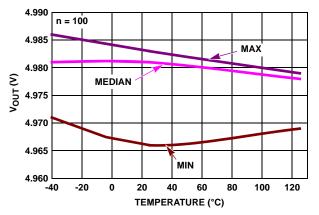
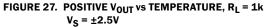


FIGURE 26. PSRR vs TEMPERATURE ±1.5V TO ±2.5V





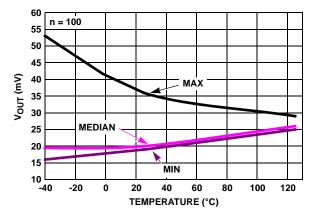


FIGURE 28. NEGATIVE V_{OUT} vs TEMPERATURE, R_L = 1k $V_S = \pm 2.5V$

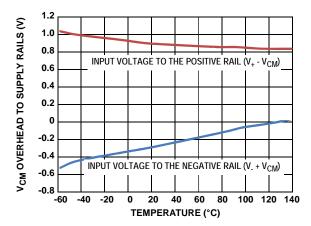


FIGURE 29. INPUT COMMON MODE VOLTAGE vs TEMPERATURE

Applications Information

Product Description

The ISL28191 and ISL28291 are voltage feedback operational amplifiers designed for communication and imaging applications requiring low distortion, very low voltage and current noise. Both parts feature high bandwidth while drawing moderately low supply current. They use a classical voltage-feedback topology, which allows them to be used in a variety of applications where currentfeedback amplifiers are not appropriate because of restrictions placed upon the feedback element used with the amplifier.

Enable/Power-Down

The ISL28191 and ISL28291 amplifiers are disabled by applying a voltage greater than 2V to the \overline{EN} pin, with respect to the V- pin. In this condition, the output(s) will be in a high impedance state and the amplifier(s) current will be reduced to $13\mu A/Amp$. By disabling the part, multiple parts can be connected together as a MUX. The outputs are tied together in parallel and a channel can be selected by the \overline{EN} pin. The \overline{EN} pin also has an internal pulldown. If left open, the \overline{EN} pin will pull to the negative rail and the device will be enabled by default.

Input Protection

All input terminals have internal ESD protection diodes to both positive and negative supply rails, limiting the input voltage to within one diode beyond the supply rails. Both parts have additional back-to-back diodes across the input terminals (as shown in Figure 30). In pulse applications where the input Slew Rate exceeds the Slew Rate of the amplifier, the possibility exists for the input protection diodes to become forward biased. This can cause excessive input current and distortion at the outputs. If overdriving the inputs is necessary, the external input current must never exceed 5mA. An external series resistor may be used to limit the current, as shown in Figure 30.

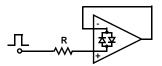


FIGURE 30. LIMITING THE INPUT CURRENT TO LESS THAN 5mA

Using Only One Channel

The ISL28291 is a dual channel op amp. If the application only requires one channel when using the ISL28291, the user must configure the unused channel to prevent it from oscillating. Oscillation can occur if the input and output pins are floating. This will result in higher than expected supply currents and possible noise injection into the channel being used. The proper way to prevent this oscillation is to short the output to the negative input and ground the positive input (as shown in Figure 31).



FIGURE 31. PREVENTING OSCILLATIONS IN UNUSED CHANNELS

Power Supply Bypassing and Printed Circuit Board Layout

As with any high frequency device, good printed circuit board layout is necessary for optimum performance. Low impedance ground plane construction is essential. Surface mount components are recommended, but if leaded components are used, lead lengths should be as short as possible. The power supply pins must be well bypassed to reduce the risk of oscillation. The combination of a 4.7μ F tantalum capacitor in parallel with a 0.01μ F capacitor has been shown to work well when placed at each supply pin.

For good AC performance, parasitic capacitance should be kept to a minimum, especially at the inverting input. When ground plane construction is used, it should be removed from the area near the inverting input to minimize any stray capacitance at that node. Carbon or Metal-Film resistors are acceptable with the Metal-Film resistors giving slightly less peaking and bandwidth because of additional series inductance. Use of sockets, particularly for the SOIC package, should be avoided if possible. Sockets add parasitic inductance and capacitance, which will result in additional peaking and overshoot.

Current Limiting

The ISL28191 and ISL28291 have no internal current-limiting circuitry. If the output is shorted, it is possible to exceed the Absolute Maximum Rating for output current or power dissipation, potentially resulting in the destruction of the device. This is why the output short circuit current is specified and tested with $R_L = 10\Omega$.

(EQ. 2)

Power Dissipation

It is possible to exceed the ± 125 °C maximum junction temperatures under certain load and power-supply conditions. It is therefore important to calculate the maximum junction temperature (T_{JMAX}) for all applications to determine if power supply voltages, load conditions, or package type need to be modified to remain in the safe operating area. These parameters are related in Equation 1:

$$\mathbf{T}_{\mathsf{JMAX}} = \mathbf{T}_{\mathsf{MAX}} + (\theta_{\mathsf{JA}} \mathbf{X} \mathsf{PD}_{\mathsf{MAXTOTAL}}) \tag{EQ. 1}$$

where:

- P_{DMAXTOTAL} is the sum of the maximum power dissipation of each amplifier in the package (PD_{MAX})
- PD_{MAX} for each amplifier can be calculated in Equation 2:

$$PD_{MAX} = 2*V_{S} \times I_{SMAX} + (V_{S} - V_{OUTMAX}) \times \frac{V_{OUTMAX}}{R_{L}}$$

where:

- T_{MAX} = Maximum ambient temperature
- θ_{JA} = Thermal resistance of the package
- PD_{MAX} = Maximum power dissipation of 1 amplifier
- V_S = Supply voltage
- I_{MAX} = Maximum supply current of 1 amplifier
- V_{OUTMAX} = Maximum output voltage swing of the application
- R_L = Load resistance

For additional products, see <u>www.intersil.com/product_tree</u>

Intersil products are manufactured, assembled and tested utilizing ISO9000 quality systems as noted in the quality certifications found at www.intersil.com/design/quality

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Revision History

The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest revision.

DATE	REVISION	CHANGE
January 18, 2012	FN6156.9	Page 1 - Ordering Information Update: Added Eval Board ISL28191EVAL1Z Changed micro TDFN and TQFN to Ultra matching POD Description Added SOT-23 Note
		Page 10 - Typical Performance Curves: Added Figure 29 - INPUT COMMON MODE VOLTAGE vs TEMPERATURE

Products

Intersil Corporation is a leader in the design and manufacture of high-performance analog semiconductors. The Company's products address some of the industry's fastest growing markets, such as, flat panel displays, cell phones, handheld products, and notebooks. Intersil's product families address power management and analog signal processing functions. Go to <u>www.intersil.com/products</u> for a complete list of Intersil product families.

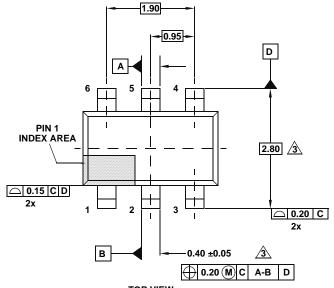
For a complete listing of Applications, Related Documentation and Related Parts, please see the respective device information page on intersil.com: <u>ISL28191,ISL28291</u>

To report errors or suggestions for this datasheet, please go to: www.intersil.com/askourstaff

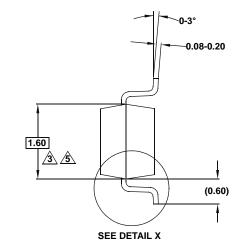
FITs are available from our website at: http://rel.intersil.com/reports/search.php

P6.064A

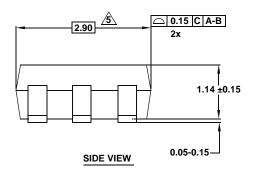
6 LEAD SMALL OUTLINE TRANSISTOR PLASTIC PACKAGE Rev 0, 2/10

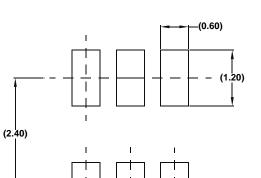


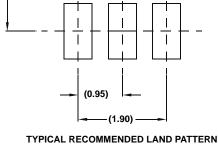
TOP VIEW

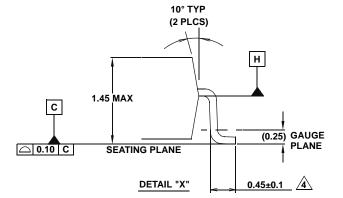


END VIEW





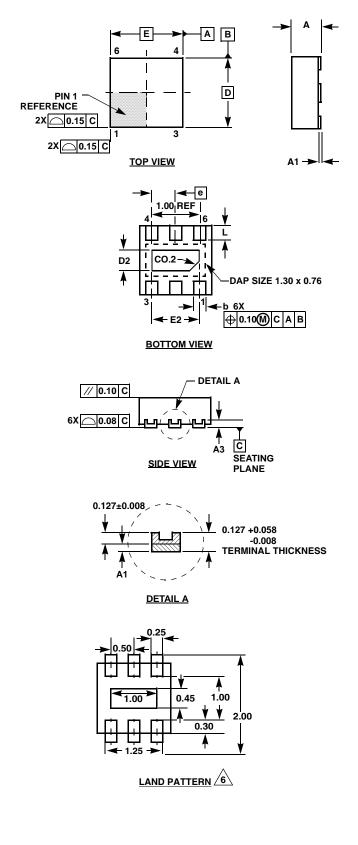




NOTES:

- 1. Dimensions are in millimeters.
- Dimensions in () for Reference Only.
- 2. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
- 3. Dimension is exclusive of mold flash, protrusions or gate burrs.
- 4. Foot length is measured at reference to guage plane.
- 5. This dimension is measured at Datum "H".
- 6. Package conforms to JEDEC MO-178AA.

Ultra Thin Dual Flat No-Lead Plastic Package (UTDFN)



L6.1.6x1.6A

6 LEAD ULTRA THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE

	Π			
SYMBOL	MIN	NOTES		
А	0.45	0.50	0.55	-
A1	-	-	0.05	-
A3		-		
b	0.15	0.20	0.25	-
D	1.55	1.60	1.65	4
D2	0.40	0.45	0.50	-
E	1.55	1.60	1.65	4
E2	0.95	1.00	1.05	-
е	0.50 BSC			-
L	0.25	0.30	0.35	-

NOTES:

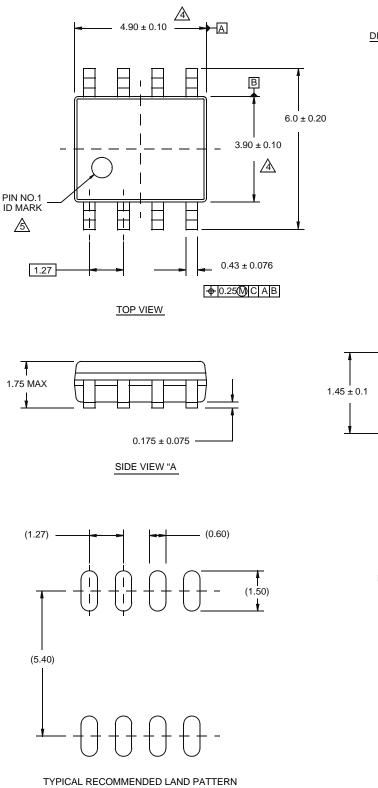
1. Dimensions are in mm. Angles in degrees.

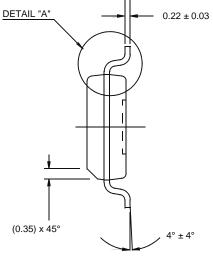
- 2. Coplanarity applies to the exposed pad as well as the terminals. Coplanarity shall not exceed 0.08mm.
- 3. Warpage shall not exceed 0.10mm.
- 4. Package length/package width are considered as special characteristics.
- 5. JEDEC Reference MO-229.
- 6. For additional information, to assist with the PCB Land Pattern Design effort, see Intersil Technical Brief TB389.

Rev. 1 6/06

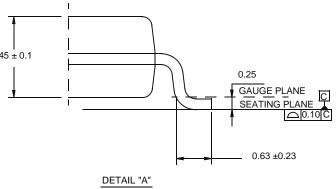
M8.15E

8 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE Rev 0, 08/09





SIDE VIEW "B"

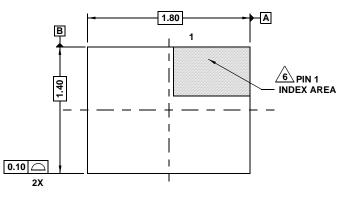


NOTES:

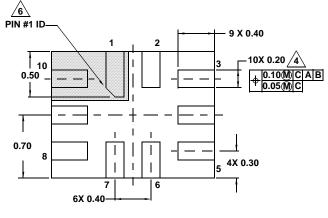
- 1. Dimensions are in millimeters. Dimensions in () for Reference Only.
- 2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
- 3. Unless otherwise specified, tolerance : Decimal ± 0.05
- 4. Dimension does not include interlead flash or protrusions. Interlead flash or protrusions shall not exceed 0.25mm per side.
- 5. The pin #1 identifier may be either a mold or mark feature.
- 6. Reference to JEDEC MS-012.

L10.1.8x1.4A

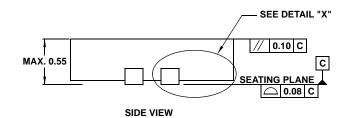
10 LEAD ULTRA THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE Rev 5, 3/10



TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN

C 0 .1 27 REF

NOTES:

- 1. Dimensions are in millimeters. Dimensions in () for Reference Only.
- 2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
- 3. Unless otherwise specified, tolerance : Decimal ± 0.05
- A. Dimension applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- 5. JEDEC reference MO-255.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.

M10.118A (JEDEC MO-187-BA)

10 LEAD MINI SMALL OUTLINE PLASTIC PACKAGE (MSOP) Rev 0, 9/09

